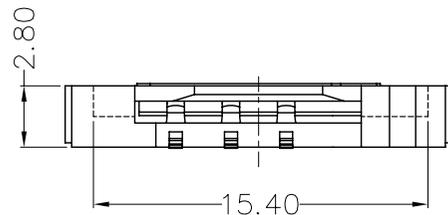
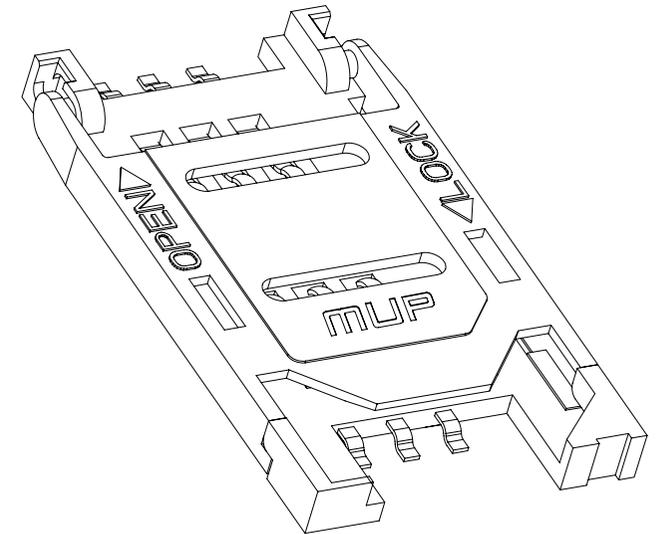
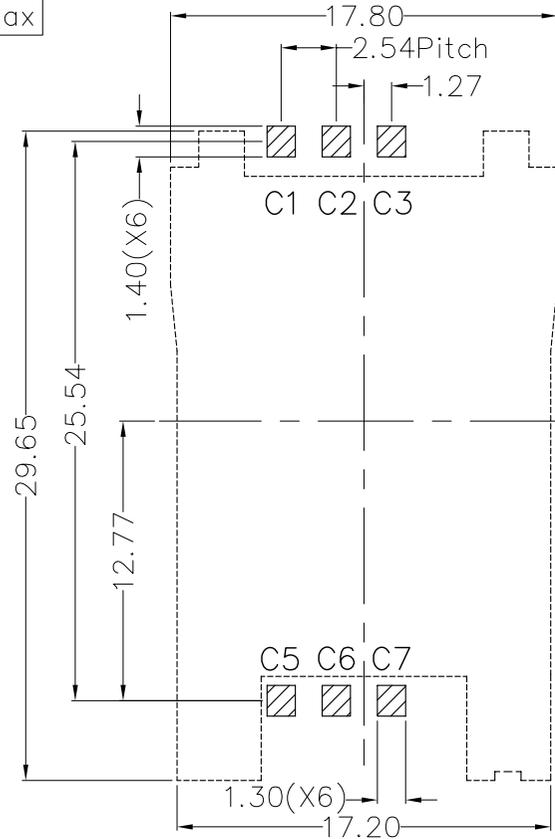
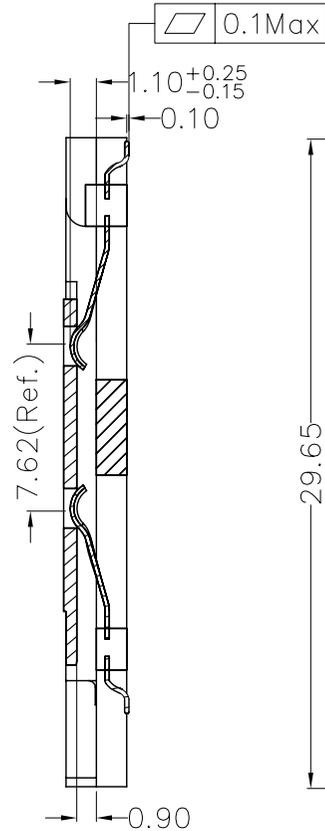
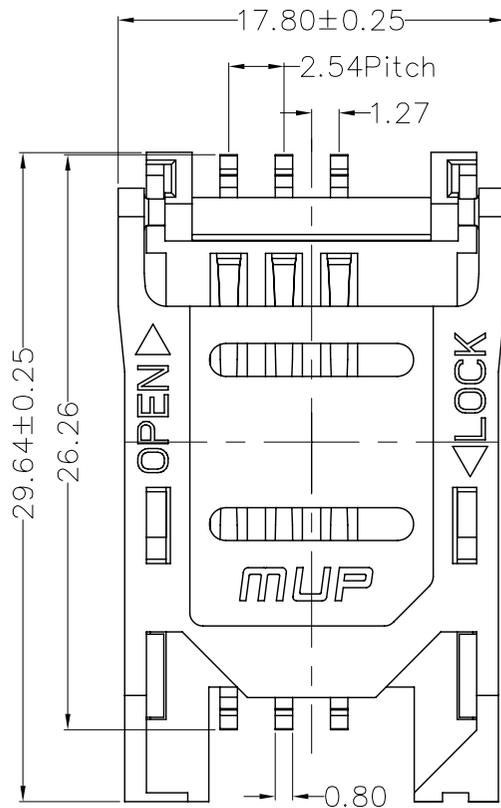


REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1					
X2					



**TECHNICAL CHARACTERISTICS**

**1.General Characteristics**

Dimensions:29.65LX17.80WX2.80H mm

Weight:Approx1.14±0.20g

Durability:5,000 cycles min.

**2.Electrical Characteristics**

Contact resistance:50mΩ typical,100mΩ max

Insulation resistance:>1000MΩ/500V DC

**3.Solderability**

IR reflow:260°C,10sec.Max

Manual soldering:370°C,3sec.Max

**4.Environmental Characteristics**

Operating temperature:-40°C~+85°C

Operating humidity:10%~+95%RH

**RECOMMENDED P.C.B LAYOUT  
COMPONENT SIDE(TOLERANCE ±0.05)**

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	BASE	1	Hi-temp Thermoplastic	Black UL94V-0
2	COVER	1	Hi-temp Thermoplastic	Black UL94V-0
3	DATA CONTACT	6	Copper Alloy	Contact area:Gold plated

Unless otherwise specified, other tolerance are:

**厦门宏端电子科技有限公司**

**NAME: SIM Card Connector**

**MODEL NO: MUP-C713(H2.80)**

**TYPE: 6pin without post**

PROJ.	UNIT	SCALE	DRAWN	Zoey Mar.10.2006	DWG NO.:
①	mm	1:1	CHECKED	Jimmy Mar.10.2006	DWG-MUP-C713-006
CUSTOMER DRAWING			APPROVAL	Jun Mar.10.2006	SHEET
					1/1
					REVISION
					X1

